

PCN Number:
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Product/Process Change Notification (PCN)

Customer: Newark

Date: May 2015

Customer Part # and/or Lot# affected:

- ACS756SCA-050B-PFF-T
- ACS756KCA-050B-PFF-T
- ACS756SCA-100B-PFF-T
- ACS756KCA-100B-PFF-T

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Duration of Change:

Permanent Temporary (explain)

Summary description of change: Part Change: Process Change: Other:

What is the part or process changing from (provide details)?

Allegro currently manufactures the ACS756 on a 6” line at PSL wafer FAB in Bloomington, MN.

What is the part or process changing to (describe the anticipated impact of this change on form, fit and/or function)?

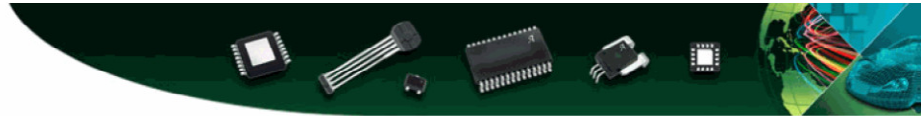
Allegro has transferred the semiconductor wafer fabrication process used to manufacture the ACS756 integrated circuit (IC) to an 8” wafer line at UMC in Taiwan, primarily as a capacity enhancement and security of supply initiative. The fabrication process at UMC uses the same BiCMOS technology used to manufacture the ACS756 at PSL today.

As part of the conversion there will be two changes internal to the CA package, related to the core and lead-frame. The external package footprint will remain unchanged.

Here is a summary of the internal package change:

	CA Package (Old)	CB Package (New)
Core Material	Ferrite	Laminated Steel
Lead-Frame buss bar width (mm)	1.7	3.2

The table outlines that the lead-frame bus-bar is wider. This wider lead-frame lowers the power dissipation of the package and improves surge current performance and is therefore an improvement to the operation of the sensor. The core material change to laminated steel provides for slightly improved magnetic offset error due to core hysteresis as well as improved saturation



performance. The sensor will perform the same or better as a true drop-in replacement over the operating temperature and frequency range specified in the datasheet.

There is no anticipated impact to fit, form or function of the IC. The schematic diagram and the layout of the ACS756 are identical at both PSL and UMC. No design changes were made during the process transfer.

Note: Validation of equivalence within a specific application is at the discretion of the Customer.

